Manual Update Sheet OMAP59xx MicroStar BGA Discontinued and Redesigned

TEXAS INSTRUMENTS

ABSTRACT

This document should be used in conjuction with the device data sheet and describes the updated package designator for the indicated devices.

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1 Package Redesign Details

Explanation

The devices in the MicroStar BGA[™] packaging were redesigned using a laminate nfBGA package. This nfBGA package offers datasheet-equivalent electrical performance. It is also footprint equivalent to the MicroStar BGA. For more details, please refer to this nfBGA Packaging Application Report.

When referencing the device data sheet, use the new package designator in place of the discontiued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nfBGA package drawing.

Table 1-1. P	ackage Des	ignator
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Old Package Designator	New Package Designator	
GZG	GVL	
ZZG	ZVL	

Reason for Discontinuance

Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior[™] BGA packaging devices and offering a Last Time Buy.

These devices have now been converted to an nfBGA package.

Devices Affected

The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

Device	Discontinued MicroStar BGA Device	Redesigned Laminate nfBGA Device	Device Data Sheet
OMAP5910	OMAP5910J GZG 2	OMAP5910J GVL 2	SPRS197, SPRS304, SPRS313
OMAP5910	OMAP5910J ZZG 2	OMAP5910J ZVL 2	SPRS197, SPRS304, SPRS313
OMAP5912	OMAP5912 ZZG R	OMAP5912 ZVL R	SPRS231
OMAP5912	OMAP5912 ZZG	OMAP5912 ZVL	SPRS231

Table 1-2. Devices and Nomenclature

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